

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SHENZHEN HISILICON SEMICONDUCTOR CO., LTD.	10/21/2016
RECEIVING PARTY DATA	
Name:	HUAWEI TECHNOLOGIES CO., LTD.
Street Address:	Huawei Administration Building
Internal Address:	Bantian, Longgang District
City:	Shenzhen
State/Country:	CHINA
Postal Code:	518129
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14601722
CORRESPONDENCE DATA	
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ATTORNEY DOCKET NUMBER:	4202-76300 (84059184US03)
NAME OF SUBMITTER:	GRANT RODOLPH
SIGNATURE:	/Grant Rodolph/
DATE SIGNED:	10/26/2016
Total Attachments: 1	
source=84059184US03_Assignment_Agreement#page1.tif	

ASSIGNMENT AGREEMENT

WHEREAS, SHENZHEN HISILICON SEMICONDUCTOR CO., LTD. a corporation of China, located at Building G1, Huawei Industrial Base, Bantian, Longgang District, Shenzhen, P.R. China 518129, hereinafter referred to as "Assignor" is the owner of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: VIDEO PROCESSING METHOD AND APPARATUS

Filing Date: 1/21/2015

Application No.: 14/601,722

WHEREAS, HUAWEI TECHNOLOGIES CO., LTD., a corporation of China, located at Huawei Administration Building, Bantian, Longgang District, Shenzhen, 518129, Guangdong, P.R. China, hereinafter referred to as "Assignee", is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable considerations, receipt of which is hereby acknowledged by Assignor, Assignor has assigned, and by these presents do assign to Assignee all right, title, and interest in and to the invention and application and to all foreign counterparts (including patent, utility mode and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignor had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees that it will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

This ASSIGNMENT AGREEMENT is hereby agreed by both Assignee and Assignor, and comes into effect on the date when the Assignee signs this ASSIGNMENT AGREEMENT, or the date when the Assignor signs This ASSIGNMENT AGREEMENT, whichever is later.

For and on behalf of Assignor by: Zhiyun XU Date: October 21, 2016
Title: President of SHENZHEN HISILICON SEMICONDUCTOR CO., LTD.

For and on behalf of Assignee by: Yafang Sun Date: October 21, 2016
Title: President of HUAWEI TECHNOLOGIES CO., LTD.